## DESCRIPTION

The AMC3202 is a 280 kHz switching regulator with a high efficiency, 1.5 A integrated switch. The part operates over a wide input voltage range, from 2.7 V to 30 V . The AMC3202 utilizes current mode architecture, which allows excellent load and line regulation, as well as a practical means for limiting current. Combining high frequency operation with a highly integrated regulator circuit results in an extremely compact power supply solution.

Build-in thermal protection to prevent the chip over heat damage.

## TYPICAL APPLICATION CIRCUIT



### 1.5A 280kHz Boost Regulators

## FEATURES

■ Integrated Power Switch: 1.5A Guaranteed.
■ Wide Input Range: 2.7 V to 30 V .

- 40V Build-in Power Switch Input Voltage.
- High Frequency Allows for Small Components.
- Minimum External Components.

- TFT-LCD Power Management
- LED Backlight


## PACKAGE PIN OUT



SO-8 (Top View)

## ORDER INFORMATION

| DM | SO |
| :---: | :---: |
|  | 8 pin |
| Note:All surface-mount packages are available in Tape \& Reel. Append the letter "T" to part number (i.e. AMC3202DMFT). The letter "F" is <br> marked for Lead Free process. |  |

AMC3202

## ABSOLUTE MAXIMUM RATINGS (Note)

| Input Voltage, $\mathrm{V}_{\mathrm{CC}}$ | 30 V |
| :--- | :--- |
| Switch Input Voltage, $\mathrm{V}_{\mathrm{SW}}$ | 40 V |
| Maximum Operating Junction Temperature, $\mathrm{T}_{\mathrm{J}}$ | $150^{\circ} \mathrm{C}$ |
| Storage Temperature Range | $-65^{\circ} \mathrm{C}$ to $150^{\circ} \mathrm{C}$ |
| Lead Temperature (Soldering, 10 seconds) | $260^{\circ} \mathrm{C}$ |
| Note: Exceeding these ratings could cause damage to the device. All voltages are with respect to Ground. <br> Currents are positive into, negative out of the specified terminal. |  |

## BLOCK DIAGRAM



| PIN DESCRIPTION |  |
| :---: | :---: |
| Pin Name | Pin Function |
| COMP | Loop compensation pin. This pin is the output of the error amplifier and is used for loop compensation. Loop compensation can be implemented by a simple RC network. |
| FB | Feedback pin. Sense the output voltage and referenced to 1.276 V . When the voltage at this pin falls below 0.4 V , chip switching-frequency reduces to a much lower frequency. |
| NC | No connection. Keep floating. |
| EN | Enable pin. A TTL low will shut down the chip and high enable the chip. This pin may also be used to synchronize the part to nearly twice the base frequency. If synchronization is not used, this pin should be either tied high or left floating for normal operation. |
| VCC | Input power supply pin. Supply power to the IC and should have a bypass capacitor connected to AGND. |
| AGND | Analog ground. Provide a clean ground for the controller circuitry and should not be in the path of large currents. This pin is connected to the IC substrate. |
| PGND | Power ground. This pin is the ground connection for the emitter of the power switching transistor. Connection to a good ground plane is essential. |
| $\mathrm{V}_{\mathrm{SW}}$ | High current switch pin. Connect to the collector of the internal power switch. The open voltage across the power switch can be as high as 40 V . To minimize radiation, use a trace as short as practical. |
| Exposed Pad (PGND) | Heat pad. Connect to power ground. Must be soldered to electrical ground on PCB. |
| THERMAL DATA |  |
| Thermal Resist | are from Junction to Ambient, $\theta_{\text {JA }} \quad 165^{\circ} \mathrm{C} / \mathrm{W}$ |
| Junction Temperatu The $\theta_{\mathrm{IA}}$ numbers ar Connect the groun All of the above as | Calculation: $\quad T_{J}=T_{A}+\left(P_{D} \times \theta_{J A}\right)$. <br> guidelines for the thermal performance of the device/pc-board system. in to ground using a large pad or ground plane for better heat dissipation. me no ambient airflow. |

## Maximum Power Calculation:

$\mathrm{P}_{\mathrm{D}(\mathrm{MAX})}=\frac{\mathrm{T}_{\mathrm{J}(\mathrm{MAX})}-\mathrm{T}_{\mathrm{A}(\mathrm{MAX})}}{\theta_{\mathrm{JA}}}$
$\mathrm{T}_{\mathrm{J}}\left({ }^{\circ} \mathrm{C}\right): \quad$ Maximum recommended junction temperature
$\mathrm{T}_{\mathrm{A}}\left({ }^{\circ} \mathrm{C}\right): \quad$ Ambient temperature of the application
$\theta_{\mathrm{JA}}\left({ }^{\circ} \mathrm{C} / \mathrm{C}\right): \quad$ Junction-to-Ambient thermal resistance of the package, and other heat dissipating materials.

## The maximum power dissipation for a single-output regulator is:



## RECOMMENDED OPERATING CONDITIONS

| Parameter | Symbol | Min | Typ | Max | Unit |
| :--- | :---: | :---: | :---: | :---: | :---: |
| Supply Voltage | $\mathrm{V}_{\mathrm{IN}}$ | 2.7 |  | 30 | V |
| Average Supply Current | $\mathrm{I}_{\mathrm{IN}}$ |  |  | 1.3 | A |
| Output Voltage | $\mathrm{V}_{\text {OUT }}$ |  |  | 39 | V |
| Operating Free-air Temperature Range | $\mathrm{T}_{\mathrm{A}}$ |  |  | $85^{\circ} \mathrm{C}$ | ${ }^{\circ} \mathrm{C}$ |

## DC ELECTRICAL CHARACTERISTICS

| $\mathrm{V}_{\mathrm{CC}}=3.3 \mathrm{~V}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$, (Unless otherwise noted) |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Parameter | Conditions | Min | Typ | Max | Unit |
| FB Reference Voltage | COMP tied to FB; Measure at FB; $2.7 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 30 \mathrm{~V}$ | 1.246 | 1.276 | 1.300 | V |
| FB Input Current | $\mathrm{FB}=\mathrm{V}_{\text {REF }}$ | -1.0 | 0.1 | 1.0 | uA |
| FB Reference Voltage Line Regulation | $\mathrm{COMP}=\mathrm{FB}, 2.7 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 30 \mathrm{~V}$ | - | 0.01 | 0.03 | \%/V |
| Error Amp Transconductance | $\mathrm{I}_{\text {COMP }}= \pm 25 \mathrm{uA}^{\text {(Note) }}$ | 300 | 550 | 800 | uMho |
| Error Amp Gain | (Note) | 200 | 500 | - | V/V |
| COMP Source Current | $\mathrm{FB}=1.0 \mathrm{~V}, \mathrm{COMP}=1.25 \mathrm{~V}$ | 25 | 50 | 90 | uA |
| COMP Sink Current | $\mathrm{FB}=1.5 \mathrm{~V}, \mathrm{COMP}=1.25 \mathrm{~V}$ | 200 | 625 | 1500 | uA |
| COMP High Clamp Voltage | $\mathrm{FB}=1.0 \mathrm{~V}, \mathrm{COMP}$ sources 25 uA | 1.5 | 1.7 | 1.9 | V |
| COMP Low Clamp Voltage | $\mathrm{FB}=1.5 \mathrm{~V}, \mathrm{COMP}$ sinks 25 uA | 0.25 | 0.50 | 0.65 | V |
| COMP Threshold | Reduce COMP from 1.5 V until switching stops | 0.75 | 1.05 | 1.30 | V |
| Base Operating Frequency | $\mathrm{FB}=1 \mathrm{~V}$ | 230 | 280 | 310 | kHz |
| Reduced Operating Frequency | $\mathrm{FB}=0 \mathrm{~V}$ | 30 | 52 | 120 | kHz |
| Maximum Duty Cycle | $\mathrm{FB}=1 \mathrm{~V}$ | 90 | 94 | - | \% |
| FB Frequency Shift Threshold | Frequency drops to reduced operating frequency | 0.36 | 0.40 | 0.44 | V |
| Synchronization Range |  | 320 | - | 500 | kHz |
| Synchronization Pulse Transition Threshold | Rise time $=20 \mathrm{~ns}$ | 2.5 | - | - | V |
| EN Bias Current | $\begin{aligned} & \mathrm{EN}=0 \mathrm{~V} \\ & \mathrm{EN}=3.0 \mathrm{~V} \end{aligned}$ | $-15$ | $\begin{gathered} -3.0 \\ 3.0 \\ \hline \end{gathered}$ | $8.0$ | uA |
| Shutdown Threshold |  | 0.50 | 0.85 | 1.20 | V |
| Shutdown Delay | $\begin{aligned} & 2.7 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 12 \mathrm{~V} \\ & 12 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 30 \mathrm{~V} \\ & \hline \end{aligned}$ | $\begin{aligned} & 12 \\ & 12 \end{aligned}$ | $\begin{aligned} & 80 \\ & 36 \\ & \hline \end{aligned}$ | $\begin{aligned} & 350 \\ & 200 \\ & \hline \end{aligned}$ | uS |


| Switch Saturation Voltage | $\begin{aligned} & \mathrm{I}_{\text {SWITCH }}=1.5 \mathrm{~A} \\ & \mathrm{I}_{\text {SIITCH }}=1.0 \mathrm{~A}, 0^{\circ} \mathrm{C} \leqq \mathrm{~T}_{\mathrm{J}} \leqq 85^{\circ} \mathrm{C}^{\text {(Note) }} \\ & \mathrm{I}_{\text {SIITCH }}=1.0 \mathrm{~A},-40^{\circ} \mathrm{C} \leqq \mathrm{~T}_{\mathrm{J}} \leqq 0^{\circ} \mathrm{C} \text { (Note) } \\ & \mathrm{I}_{\text {SWITCH }}=10 \mathrm{~mA} \end{aligned}$ |  | $\begin{gathered} 0.8 \\ 0.55 \\ 0.75 \\ 0.09 \end{gathered}$ | $\begin{gathered} 1.4 \\ - \\ - \\ 0.45 \end{gathered}$ | V |
| :---: | :---: | :---: | :---: | :---: | :---: |
| Switch Current Limit | $\begin{aligned} & 50 \% \text { duty cycle }^{\text {(Note) }} \\ & 80 \% \text { duty cycle }^{\text {(Note) }} \\ & \hline \end{aligned}$ | $\begin{aligned} & 1.6 \\ & 1.5 \\ & \hline \end{aligned}$ | $\begin{aligned} & 1.9 \\ & 1.7 \\ & \hline \end{aligned}$ | $\begin{aligned} & 2.4 \\ & 2.2 \end{aligned}$ | A |
| Minimum Pulse Width | COMP $=1.4 \mathrm{~V}, \mathrm{I}_{\text {SW }}=1.0 \mathrm{~A}$ | 100 | 250 | 300 | nS |
| Switch Leakage | $\mathrm{V}_{\mathrm{SW}}=40 \mathrm{~V}, \mathrm{~V}_{\mathrm{CC}}=0 \mathrm{~V}$ | - | 2.0 | 100 | uA |
| $\Delta \mathrm{I}_{\mathrm{CC}} / \Delta \mathrm{I}_{\text {sw }}$ | $\begin{aligned} & 2.7 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 12 \mathrm{~V}, 10 \mathrm{~mA} \leqq \mathrm{I}_{\mathrm{SW}} \leqq 1.0 \mathrm{~A} \\ & 12 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 30 \mathrm{~V}, 10 \mathrm{~mA} \leqq \mathrm{I}_{\mathrm{SW}} \leqq 1.0 \mathrm{~A} \\ & 2.7 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 12 \mathrm{~V}, 10 \mathrm{~mA} \leqq \mathrm{I}_{\mathrm{SW}} \leqq 1.5 \mathrm{~A} \\ & 12 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 30 \mathrm{~V}, 10 \mathrm{~mA} \leqq \mathrm{I}_{\mathrm{SW}} \leqq 1.5 \mathrm{~A} \\ & \hline \end{aligned}$ | - | 10 $17$ | $\begin{gathered} 30 \\ 100 \\ 30 \\ 100 \\ \hline \end{gathered}$ | $\mathrm{mA} / \mathrm{A}$ |
| Operating Current | $\mathrm{I}_{\mathrm{SW}}=0 ; 2.7 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 30 \mathrm{~V}$ | - | 5.5 | 8.0 | mA |
| Shutdown Mode Current | COMP $<0.8 \mathrm{~V}, \mathrm{EN}=0 \mathrm{~V}, 2.7 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 12 \mathrm{~V}$ <br> COMP $<0.8 \mathrm{~V}, \mathrm{EN}=0 \mathrm{~V}, 12 \mathrm{~V} \leqq \mathrm{~V}_{\mathrm{CC}} \leqq 30 \mathrm{~V}$ | - | $12$ | $\begin{gathered} 60 \\ 100 \\ \hline \end{gathered}$ | uA |
| Minimum Operation Input Voltage | $\mathrm{V}_{\mathrm{SW}}$ switching, maximum $\mathrm{I}_{\mathrm{SW}}=10 \mathrm{~mA}$ |  | 2.45 | $2.70$ | V |
| Thermal Shutdown |  | 150 | - | - | ${ }^{\circ} \mathrm{C}$ |
| Thermal Hysteresis |  | - | 25 | - | ${ }^{\circ} \mathrm{C}$ |

Note: Guaranteed by design, not $100 \%$ tested in production.

## CHARACTERIZATION CURVES

Switch Frequency vs. FB


Reference Voltage vs. Temperature

$\mathrm{V}_{\mathrm{CE}(\mathrm{SAT})} \mathrm{vS} . \mathrm{I}_{\mathrm{SW}}$


Icc vs. $\mathrm{V}_{\mathrm{cc}}$ During Shutdowm



COMP Threshold vs. Temperature


Shutdown Delay vs. Temperature


Minimum $\mathrm{V}_{\mathrm{cc}}$ vs. Temperature


Max Duty Cycle vs. Temperature


## APPLICATION INFORMATION

## Operation:

The AMC3202 incorporates a current mode control scheme, in which the duty cycle of the switch is directly controlled by switch current rather than by output voltage. The output of the oscillator turns on the power switch at a frequency of 280 kHz as shown in the block diagram. The power switch is turned off by the output of the PWM comparator.

A TTL low voltage will shut down the chip and high voltage enable the chip through EN pin. This pin may also be used to synchronize the part to nearly twice the base oscillator frequency. In order to synchronize to a higher frequency, a positive transition turns on the power switch before the output of the oscillator goes high, thereby resetting the oscillator. The synchronization operation allows multiple power supplies to operate at the same frequency. If synchronization is not used, this pin should be either tied high or left floating for normal operation.

## Component Selection:



The $\mathrm{V}_{\text {IN }}$ ripple is determined by the product of the inductor current ripple and the ESR of input capacitor, and the $V_{\text {out }}$ ripple comes from two major sources, namely ESR of output capacitor and the charging/discharging of the output capacitor. Ceramic capacitors have the lowest ESR, but too low ESR may cause loop stability problems. Aluminum Electrolytic capacitors exhibit the highest ESR, resulting in the poorest AC response. One option is to parallel a ceramic capacitor with an Aluminum Electrolytic capacitor.

## Frequency Compensation

The goal of frequency compensation is to achieve desirable transient response and DC regulation while ensuring the stability of the system. A typical compensation network, as shown in the typical application circuit, provides a frequency response of two poles and one zero. The loop frequency compensation is performed on the output of the error amplifier (COMP pin) with a series RC network. The main pole is formed by the series capacitor and the output impedance of the error amplifier. The series resistor creates a zero, which improves loop stability and transient response. A second capacitor is sometimes used to reduce the switching frequency ripple on the COMP pin.

## $f_{P 1}=\frac{1}{2 \pi C_{P 1} R_{O}} \quad$ where, $\mathrm{R}_{\mathrm{O}}=$ error amplifier output resistance; $f_{Z 1}=\frac{1}{2 \pi C_{P 1} R_{P}}$ $f_{P 2}=\frac{1}{2 \pi C_{P 2} R_{P}}$

## PACKAGE

8-Pin Plastic S.O.I.C.


| SYMBOLS | MIN. | MAX. |  |
| :---: | :---: | :---: | :---: |
| A | 0.053 | 0.069 |  |
| A1 | 0.002 | 0.006 |  |
| A2 | - | 0.059 |  |
| D | 0.189 | 0.196 |  |
| E | 0.150 | 0.157 |  |
| H | 0.228 | 0.244 |  |
| L | 0.016 | 0.050 |  |
| $\theta^{\circ}$ | 0 | 8 |  |
| UNIT: INCH |  |  |  |

THERMALLY ENHANCED DIMENSIONS

| PAD SIZE | E1 | D1 |
| :---: | :---: | :---: |
| $90 \times 90 E$ | 0.081 REF | 0.081 REF |
| $95 X 13 E$ | 0.086 REF | 0.117 REF |

## NOTES:

1. JEDEC OUTLINE. N/A
2. DIMENSIONS "D" DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS AND GATE BURRS SHALL NOT EXCEED 15 mm (.005in) PER SIDE.
3. DIMENSIONS "E" DOES NOT INCLUDE INTER-LEAD FLASH, OR PROTRUSIONS. INTER-LEAD FLASH AND PROTRUSIONS SHALL NOT EXCEED .25 mm (.010in) PER SIDE.

E.P. VERSION ONLY

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